Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model
[List multiple models if applicable.]
HP Envy Sleekbook 4 PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit</td>
<td>With a surface greater than 10 sq cm Mother board</td>
<td>1</td>
</tr>
<tr>
<td>Assemblies (PCA)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries battery and RTC battery</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater</td>
<td>Includes background illuminated displays with gas discharge lamps LCD</td>
<td>1</td>
</tr>
<tr>
<td>than 100 sq cm</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Power cords,Adapter</td>
<td>2</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink,</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>including liquids, semi-liquids (gel/paste) and toner</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.
## Tool Description

<table>
<thead>
<tr>
<th>Description #1</th>
<th>Screw driver</th>
<th>Tool Size (if applicable)</th>
<th>Philip #1 / TORX T</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #2</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

#### 3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. remove log low
2. remove K_LOCK_BRK
3. remove Battery Module
4. remove Subwoofer Module
5. remove I/O Board Module
6. remove DC_IN Brk
7. remove FAN Module
8. remove Thermal module
9. remove DC_IN_Cable
10. remove HDD assy
11. remove Card Reader PCB assy
12. remove M/B assy
13. remove Power PCB Module
14. remove Speaker Module
15. remove Display assy
16. remove TP Support Bracket
17. remove TP Module
18. remove KB Support Plate
19. remove KB Module
20. remove ESD PCB
21. divide Display assy (remove LCD Bezel)
22. divide Display assy (remove LCD Hinge Cap L-R)
23. divide Display assy (remove LCD Hinge Brk L-R)
24. divide Display assy (remove LCD Module)
25. divide Display assy (remove LVDS Cable)
26. divide Display assy (remove Antenna MIAN and AUX Cable)
27. divide Display assy (remove Webcam Module)
28. divide M/B assy (remove RJ45 Door assy)
29. divide M/B assy (remove WLAN Module)
30. divide M/B assy (remove SSD Module)
31. divide M/B assy (remove Memory Module)
32. divide HDD assy (remove HDD Cable)
33. divide HDD assy (remove HDD Brk assy)
34. divide Card Reader PCB assy (remove RTC Battery)
35. divide Card Reader PCB assy (remove TP LED Board Module)
36. divide Display assy (remove LCD cover AL skin)
37. divide Log UP assy (remove Log up AL skin)

#### 3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Step 1 Remove log low

Step 2 Remove _K_LOCK_BRK

Step 3 Remove Battery Module

Step 4 Remove Subwoofer Module

Step 5 Remove I/O Board Module

Step 6 Remove DC_IN Brk
Step 7 Remove FAN Module

Step 8 Remove Thermal Module

Step 9 Remove DC_IN Cable

Step 10 Remove HDD Assy
Step 11: Remove Card Reader PCB Assy

Step 12: Remove M/B Assy

Step 13: Remove Power PCB Assy

Step 14: Remove Speaker Module

Step 15: Remove Display Assy

Step 16: Remove TP Support Bracket
Step 17 Remove TP Module

Step 18 Remove KB Support Plate

Step 19 Remove KB Module

Step 20 Remove ESD PCB
Step 21: Divide display assembly (remove LCD bezel)

Step 22: Divide display assembly (remove LCD hinge cap L-R)

Step 23: Divide display assembly (remove LCD hinge brake L-R)

Step 24: Divide display assembly (remove LCD module)

Step 25: Divide display assembly (remove LVDS cable)

Step 26: Divide display assembly (remove Antenna MAIN and AUX cable)
Step 27 divide Display assy (remove Webcam Module)

Step 28 divide M/B Assy (remove Rj45 Door Assy)

Step 29 divide M/B Assy (remove WLAN Module)

Step 30 divide M/B Assy (SSD Module)
Step 31 divide M/B Assy (remove Memory Module)

Step 32 divide HDD Assy (remove HDD Cable)

Step 33 divide HDD Assy (remove HDD BRK Assy)

Step 34 divide Card Reader PCB Assy (remove RTC Battery)

Step 35 divide Card Reader PCB Assy (remove LED Board Module)
Step 36 divide Display assy (remove lcd cover AL skin)

Step 37 divide Log UP assy (remove Log up AL skin)